

**COURSE TITLE:** INTRODUCTION TO CMOS PROCESSING

**COURSE CODE:** EE2520

**Textbook:** Integrated Circuit Fabrication (Science and Technology)

**Authors:** James D Plummer and Peter B. Griffith

# Introduction

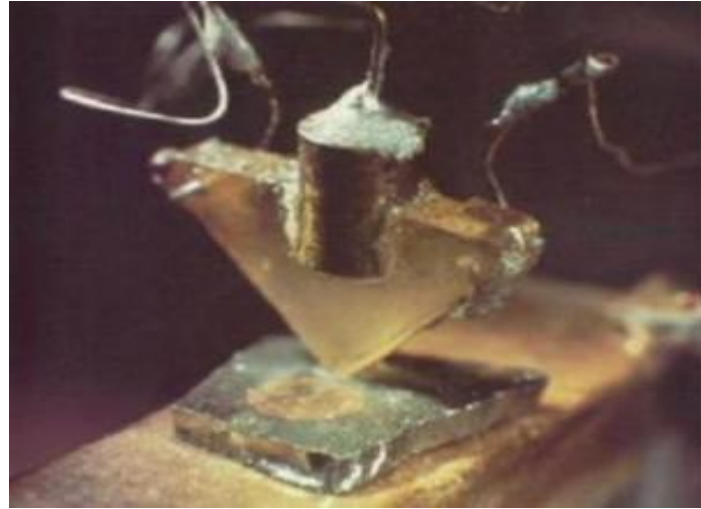
## (Lecture1)

# KEY CONCLUSIONS

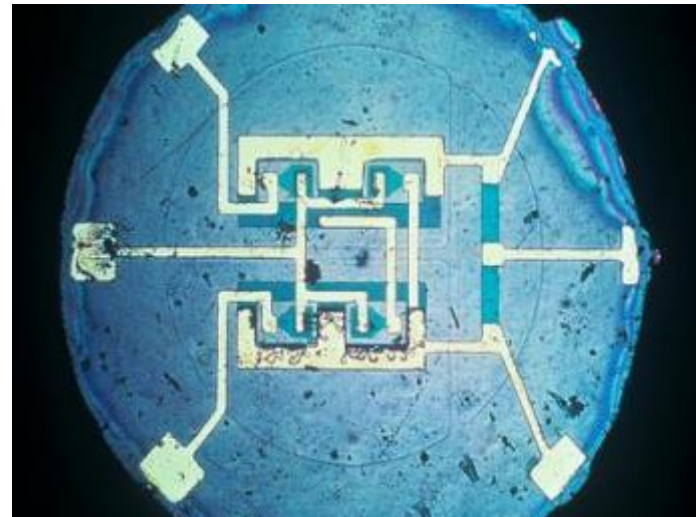
By the end of Introduction Lecture(s), you should be familiarized with

- ❖ History of Integrated Circuits
- ❖ Planar Process
- ❖ Moore's Law
- ❖ Dennard Scaling
- ❖ Technology Node
- ❖ Unit Processes
- ❖ Course Objectives

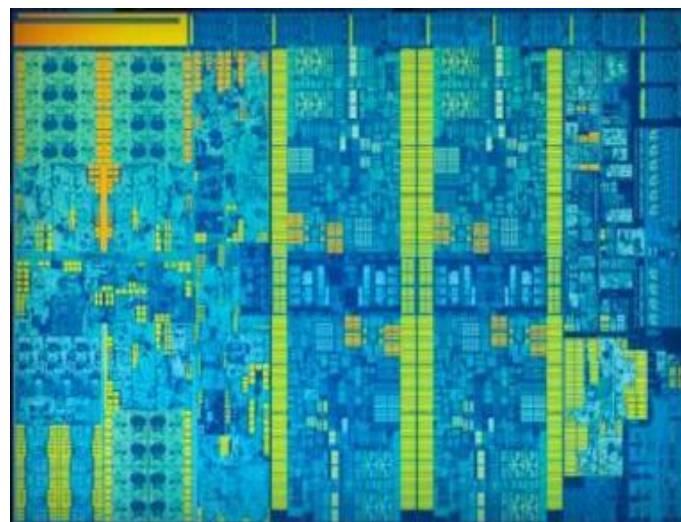
# 1948 - Present



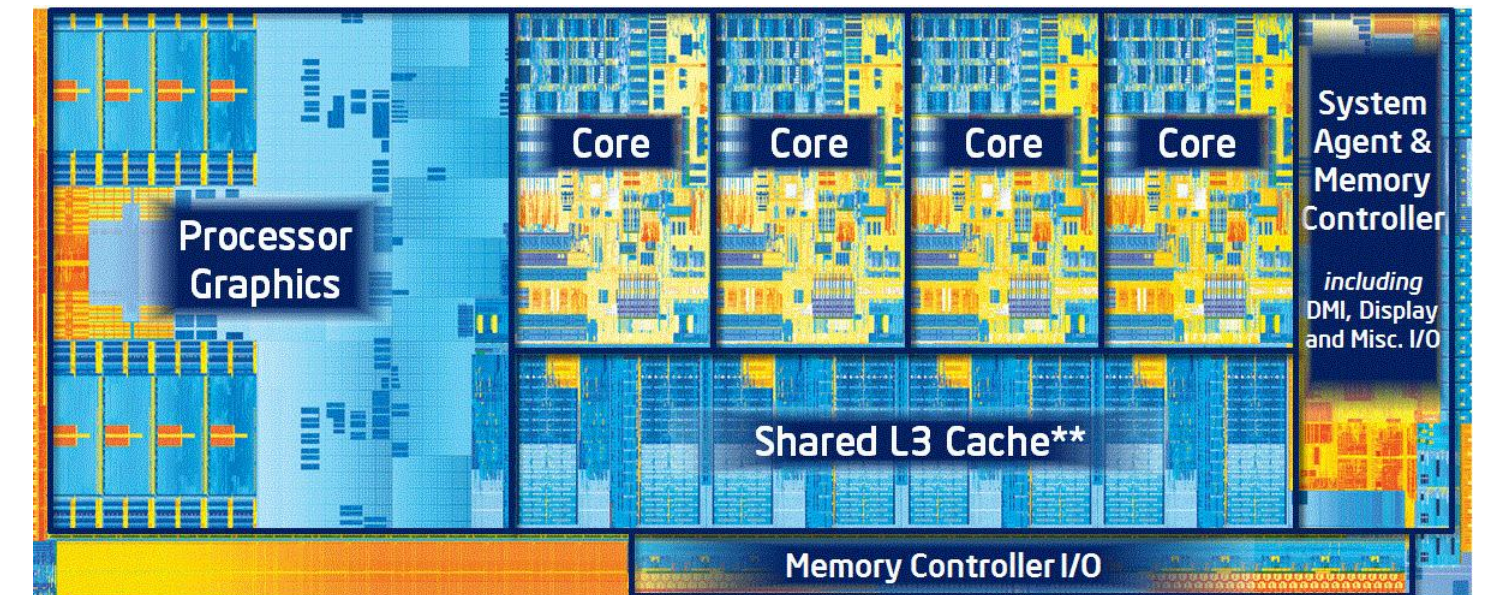
First Solid State Device



First Integrated Circuit



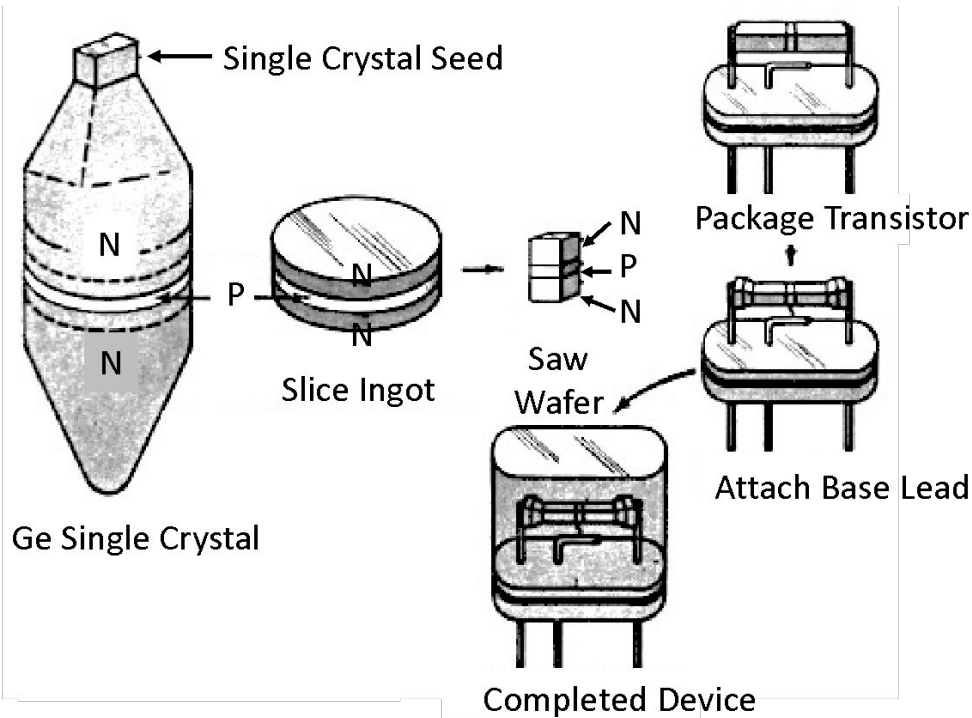
Latest Microprocessor



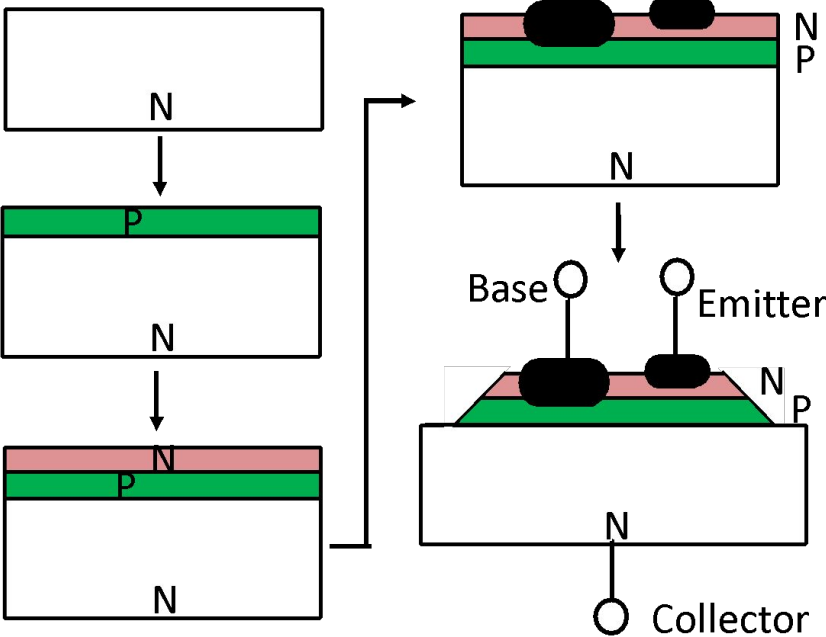
A Complex Chip (i7 processor)



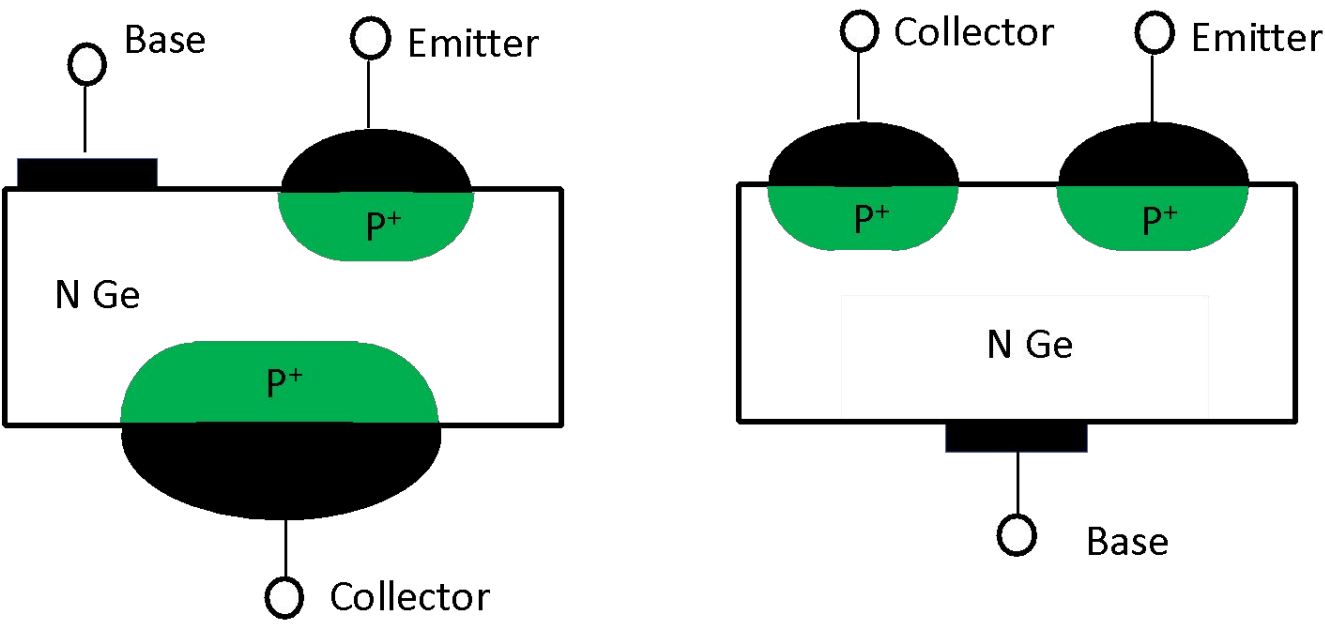
# Bulk Vs Planar



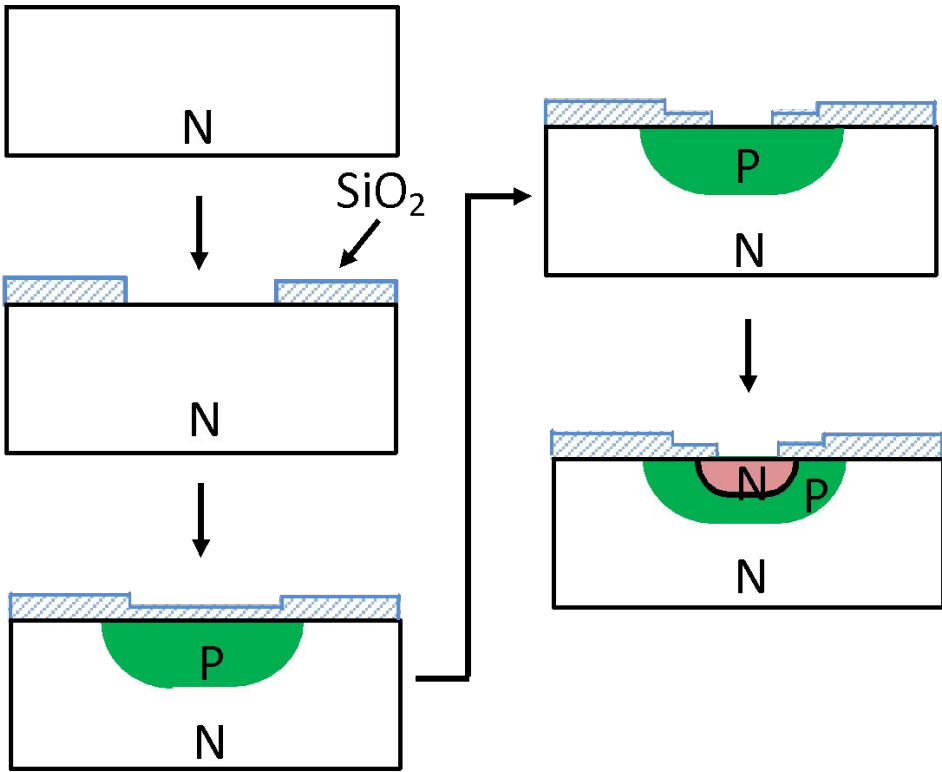
Grown junction transistor technology of the 1950s



Double diffused transistor technology of the 1950s

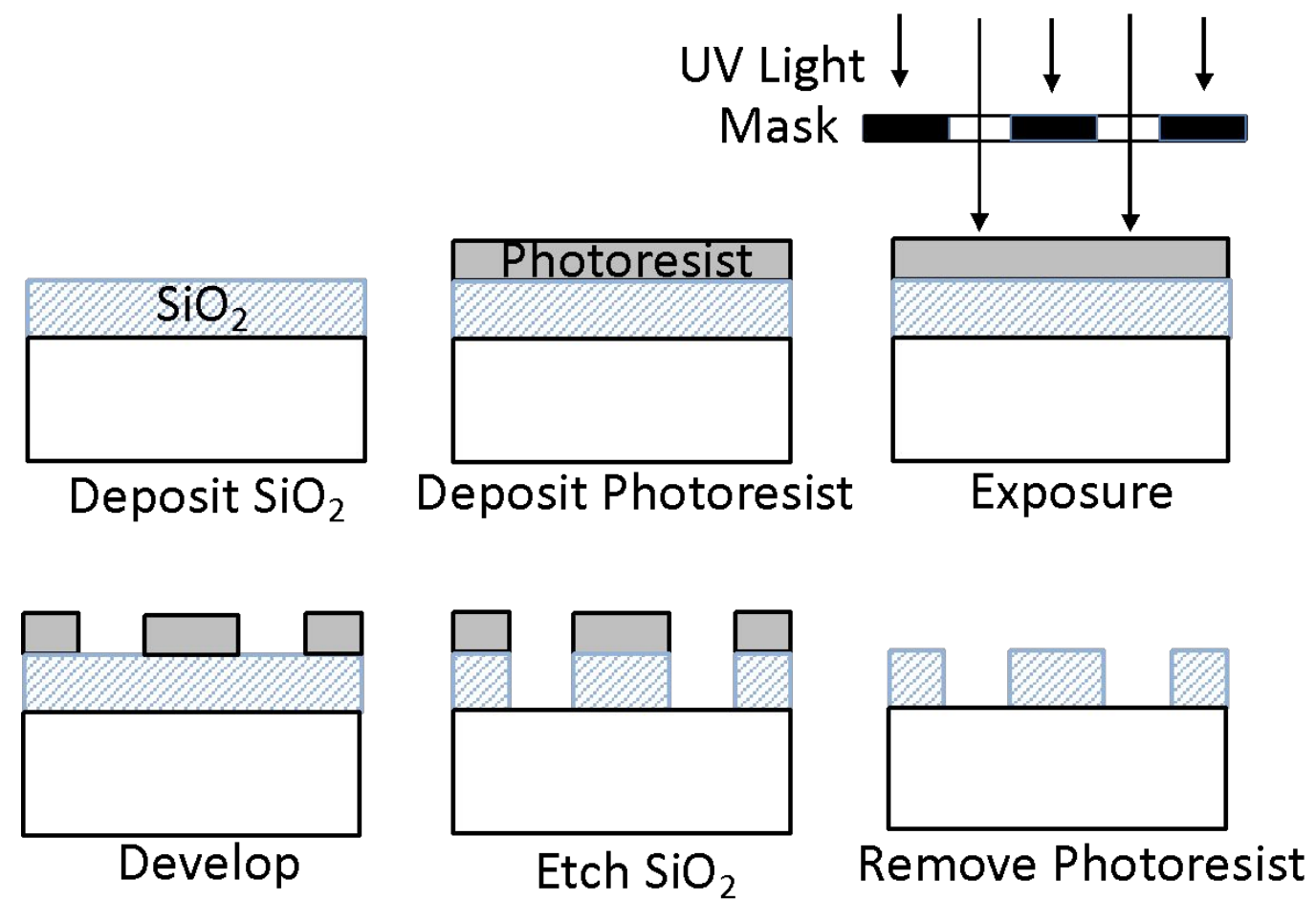


Alloy junction technology of the 1950s.

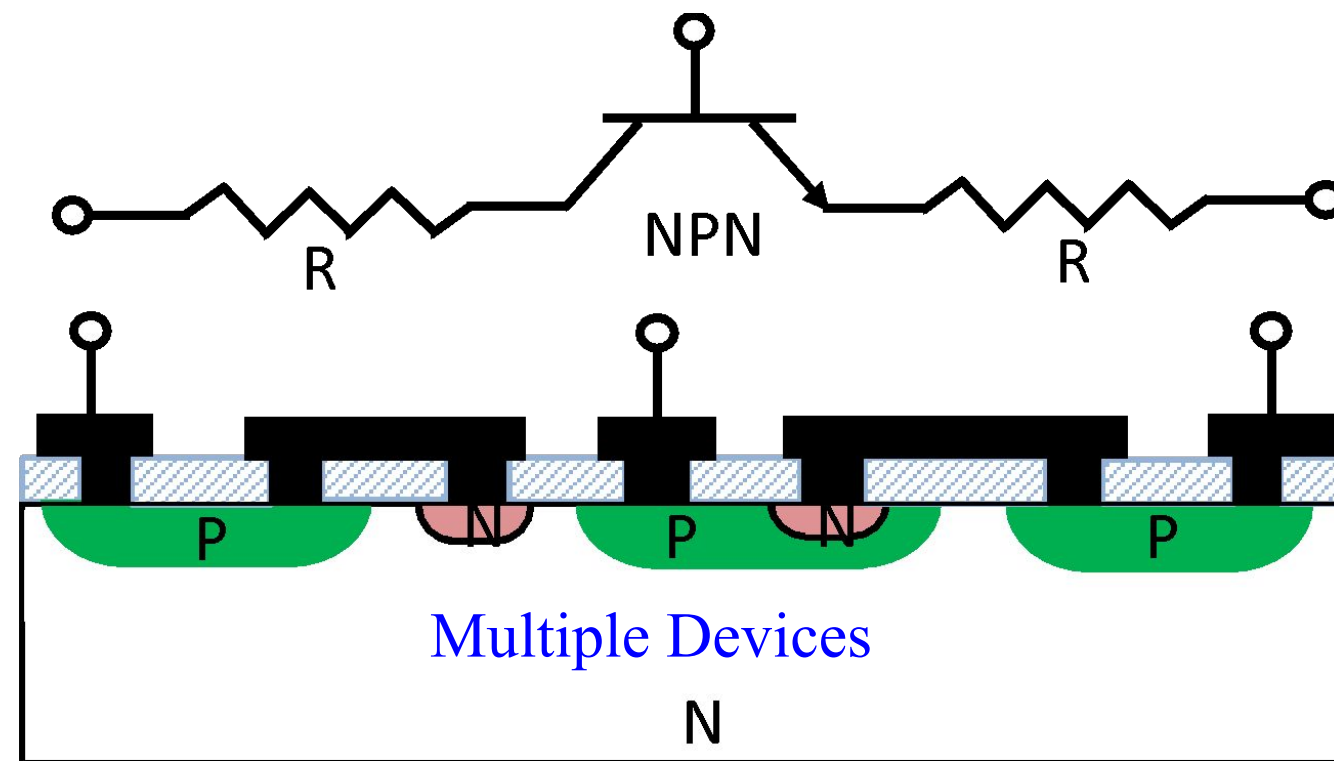


The planar process (Hoerni - Fairchild, late 1950s).

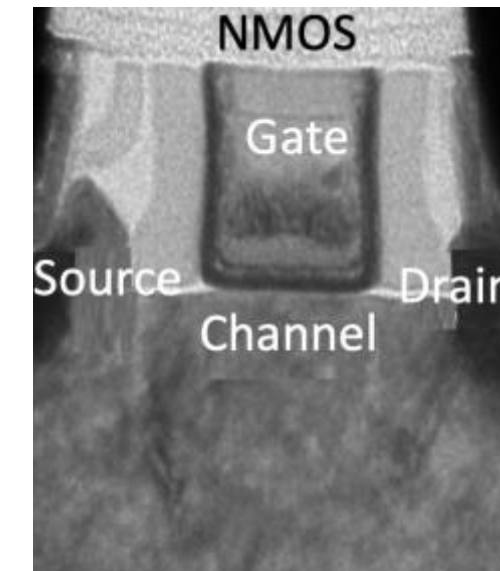
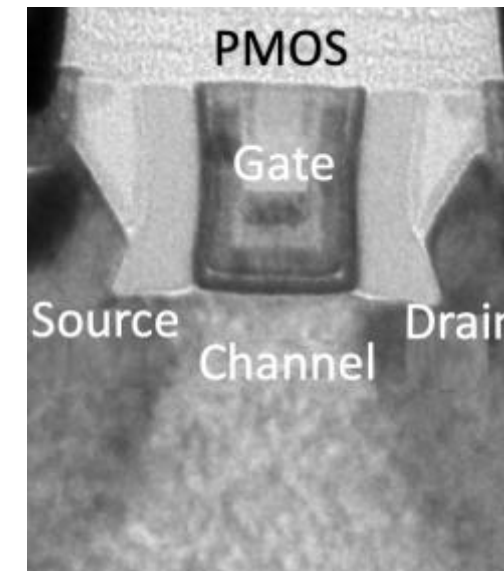
# Planar Process



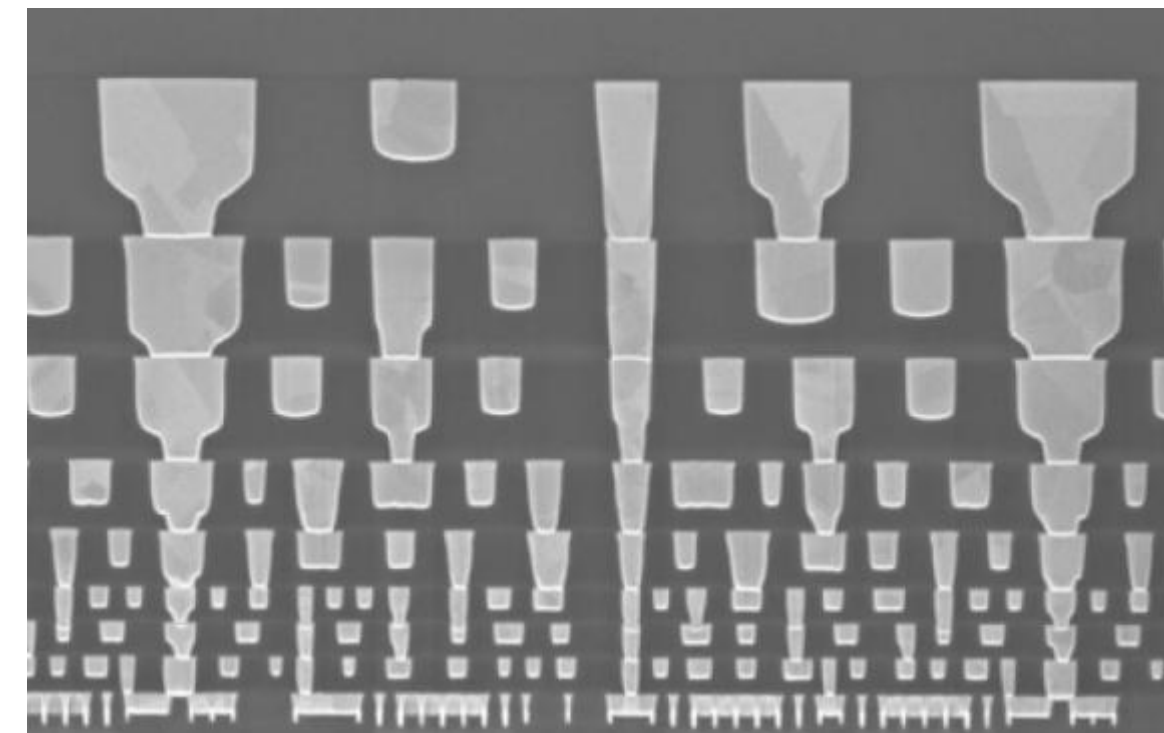
Basic lithography process



Multiple Devices

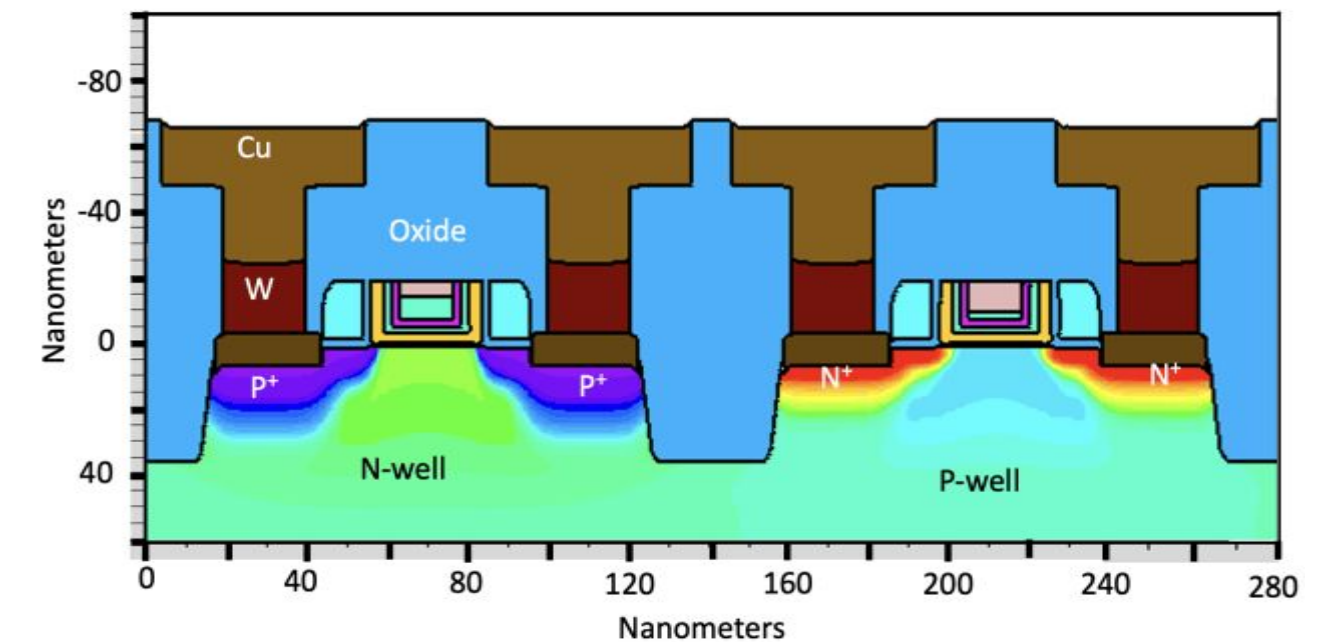
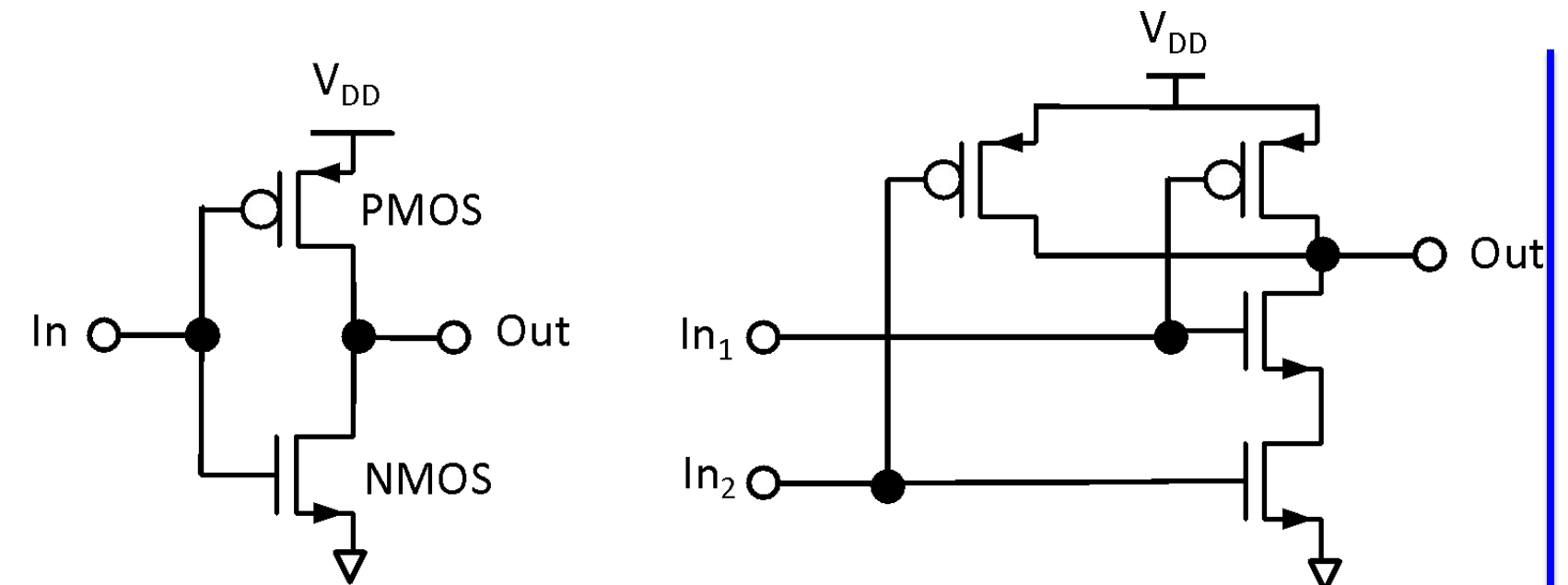
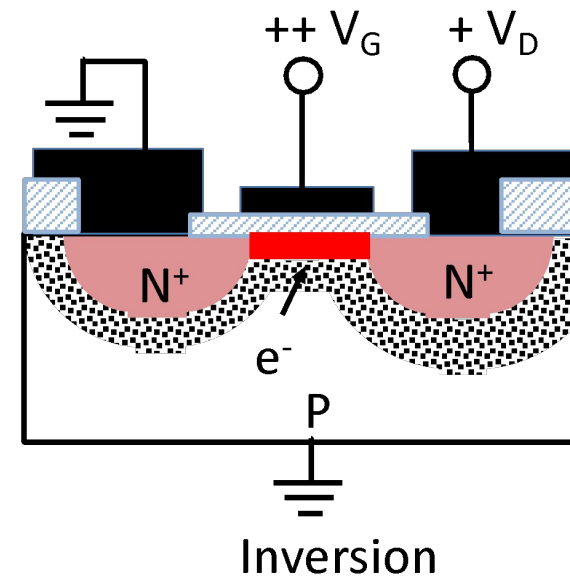
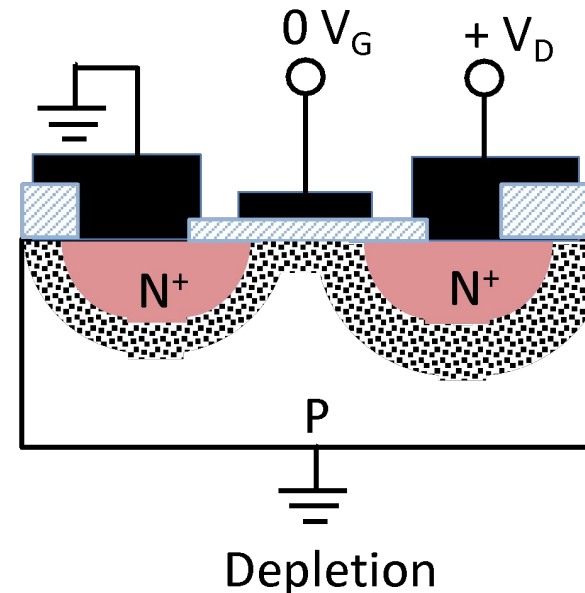
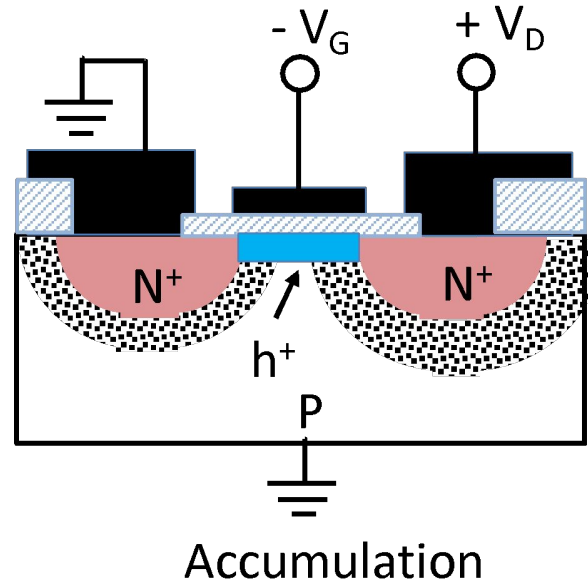
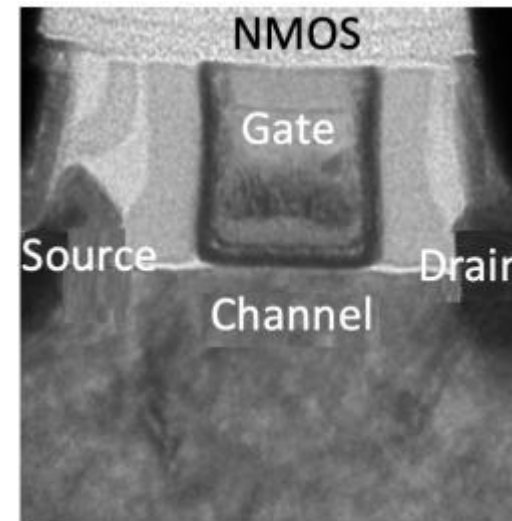
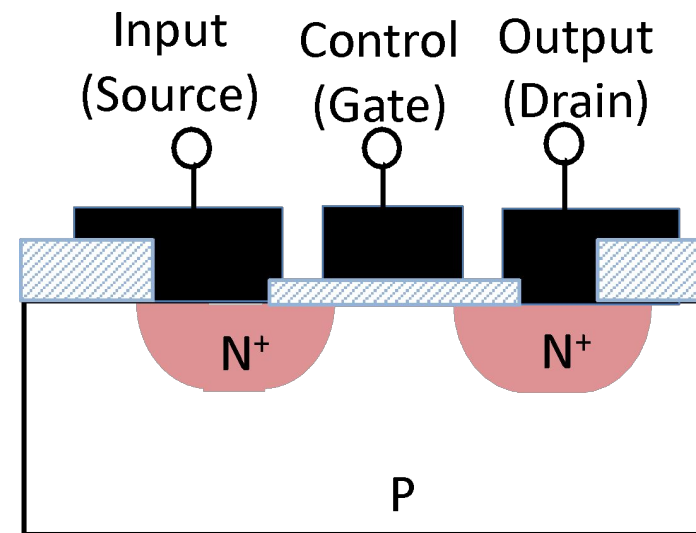
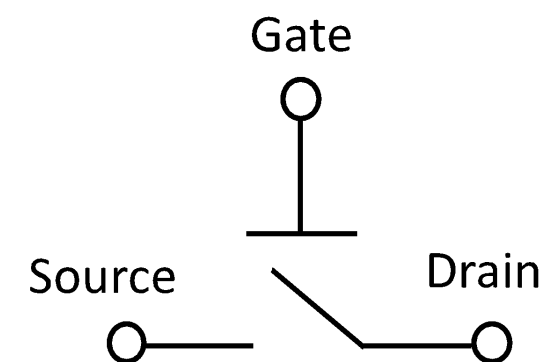


The Sub Micron Transistor



CMOS Transistors with Metal Interconnects

# MOS Vs CMOS

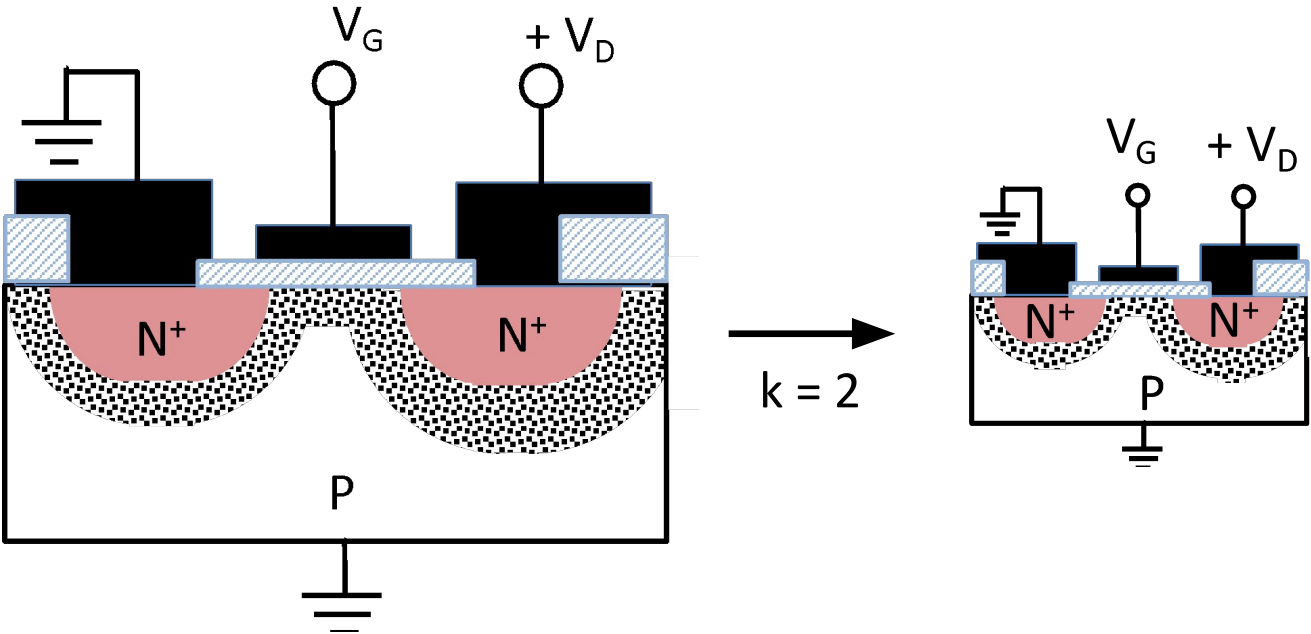


CMOS allows:

- High input impedance.
- 0 DC power dissipation.
- 0 and 1 voltage levels at Gnd and  $V_{DD}$ .
- High  $I_{ON}$ , low  $I_{OFF}$ .
- Highly flexible circuit/system design



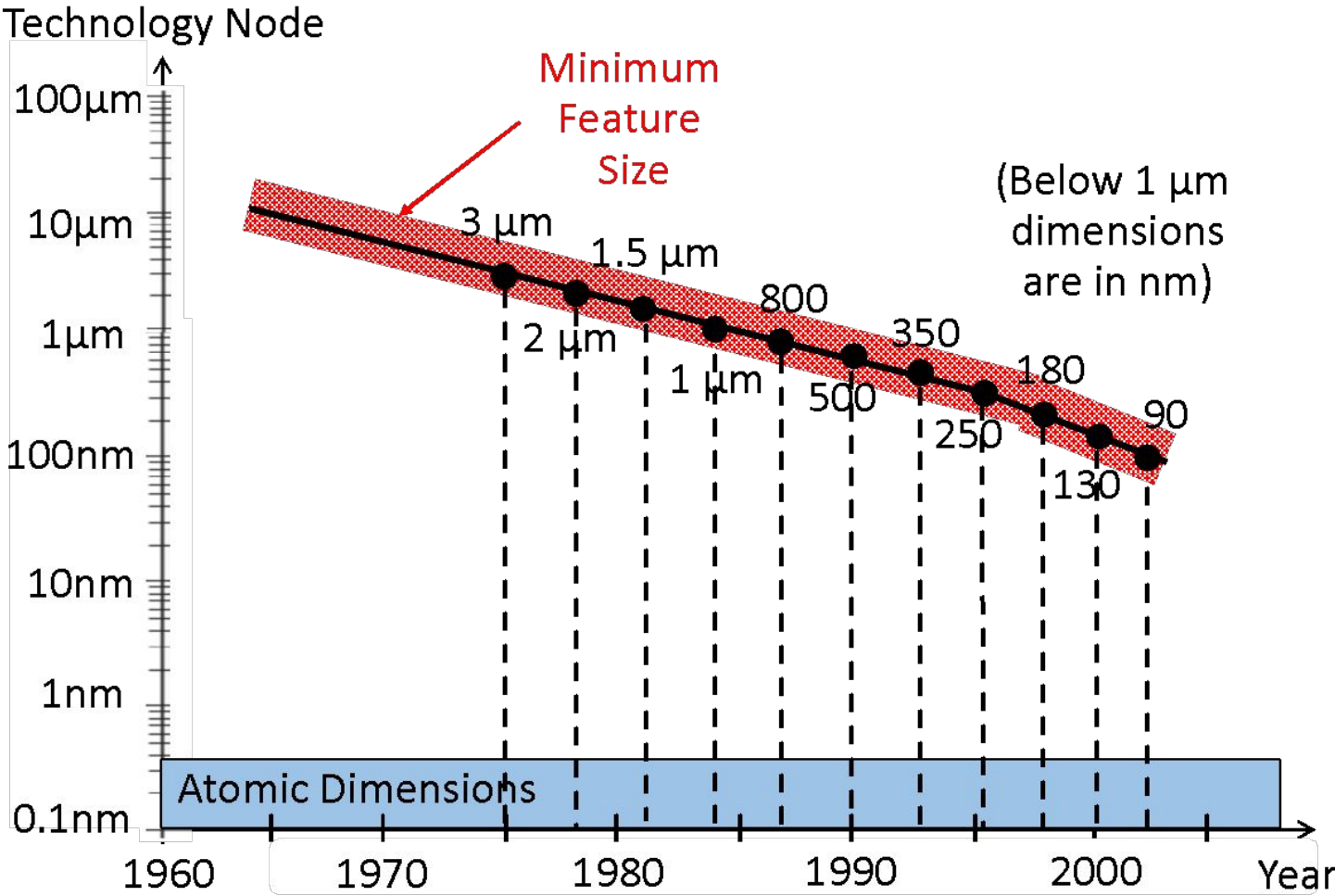
# Dennard Scaling



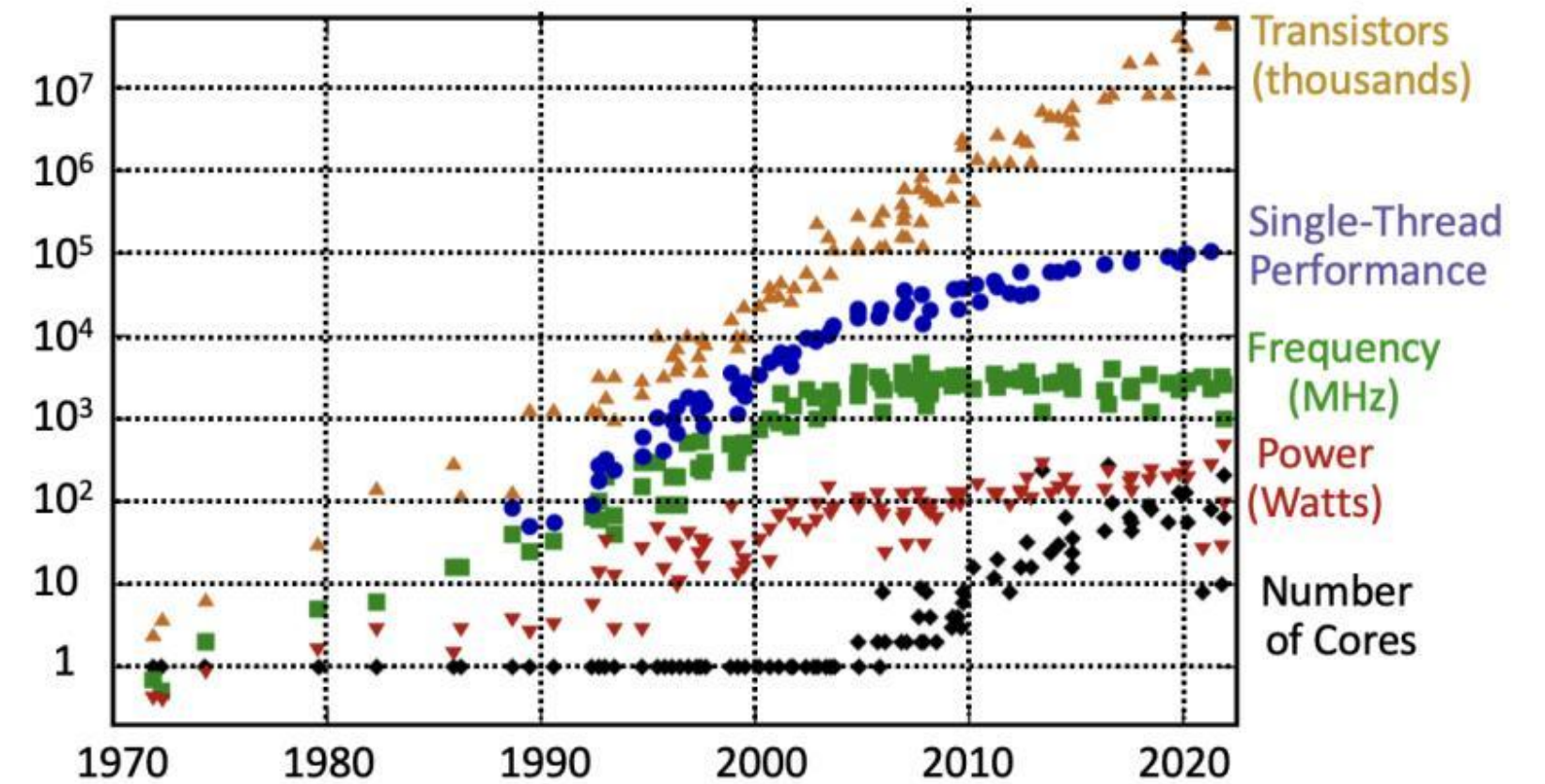
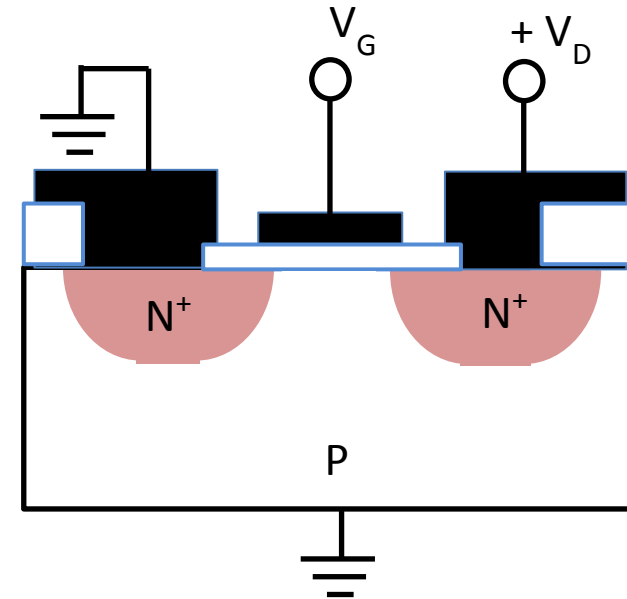
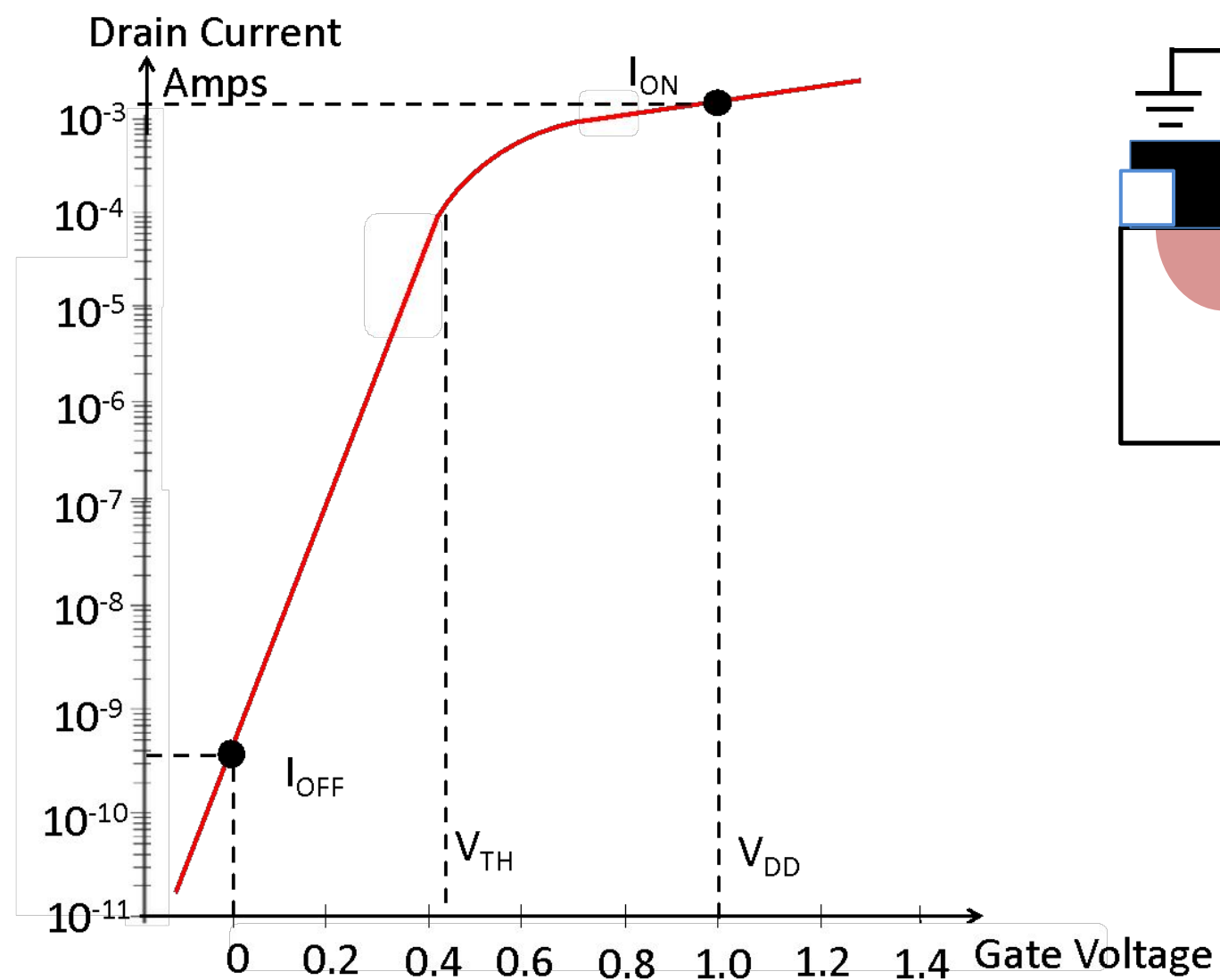
ITRS - 2003 version

| Device or Circuit Parameter       | Scaling Factor |
|-----------------------------------|----------------|
| Device Dimension, $t_{ox}$ , L, W | $1/k$          |
| Doping Concentration              | $k$            |
| Voltage V                         | $1/k$          |
| Current I                         | $1/k$          |
| Capacitance $\epsilon A/t_{ox}$   | $1/k$          |
| Delay time $VC/I$                 | $1/k$          |
| Power Dissipation VI              | $1/k^2$        |
| Power Density VI/WL               | 1              |

|                            |         |         |         |         |         |         |         |         |
|----------------------------|---------|---------|---------|---------|---------|---------|---------|---------|
| Year of Production         | 2000    | 2002    | 2004    | 2007    | 2010    | 2013    | 2016    | 2018    |
| Technology Node (nm)       | 180     | 130     | 90      | 65      | 45      | 32      | 22      | 14      |
| MPU Gate Length            | 100     | 70      | 53      | 35      | 25      | 18      | 13      | 10      |
| DRAM Bits/Chip (GB)        | .512    | 1       | 4       | 16      | 32      | 64      | 128     | 128     |
| MPU Transistors ( $10^6$ ) |         |         | 550     | 1100    | 2200    | 4400    | 8800    | 14000   |
| Supply Voltage (V)         | 1.5-1.8 | 1.2-1.5 | 0.9-1.2 | 0.8-1.1 | 0.7-1.0 | 0.6-0.9 | 0.5-0.8 | 0.5-0.7 |



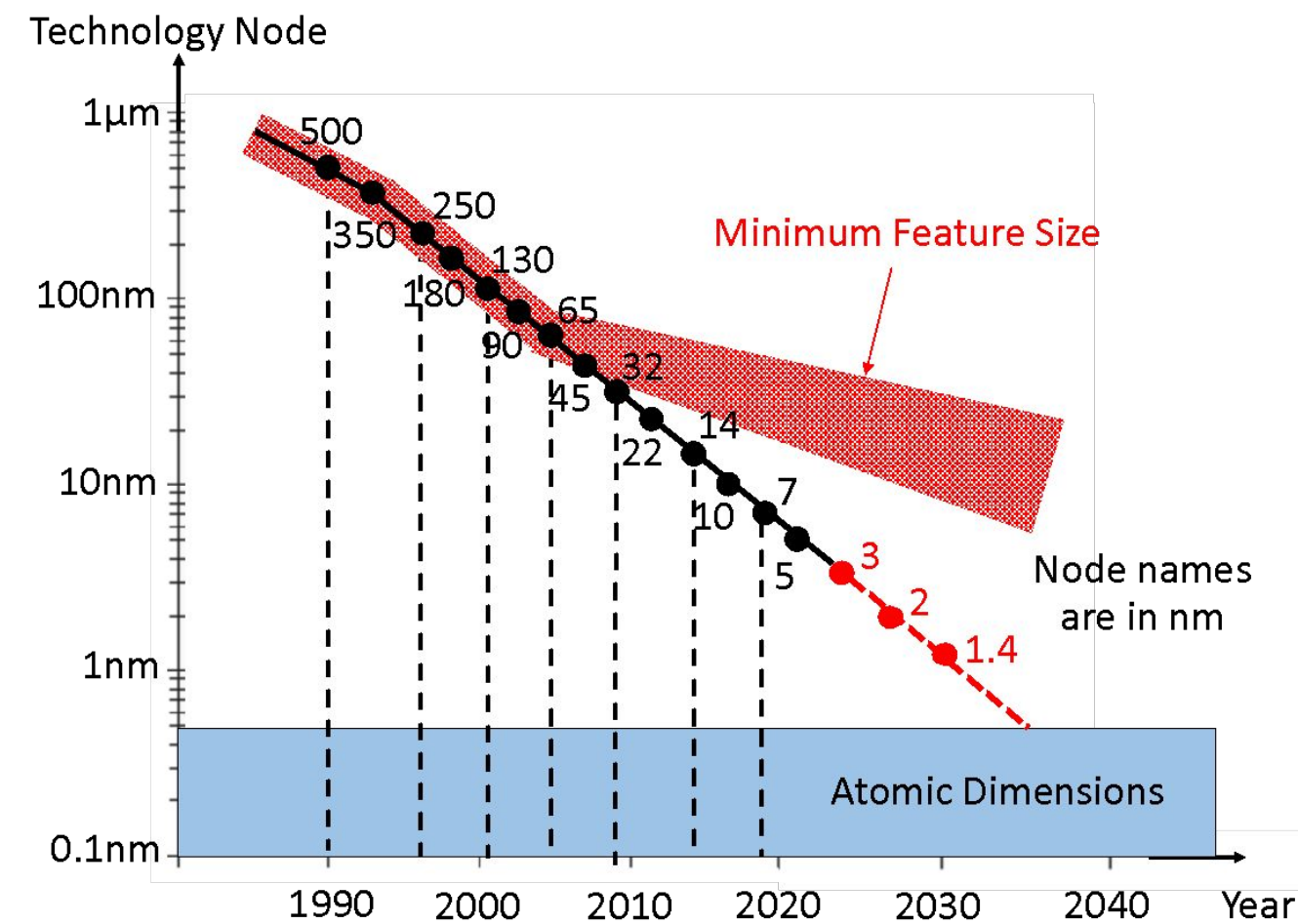
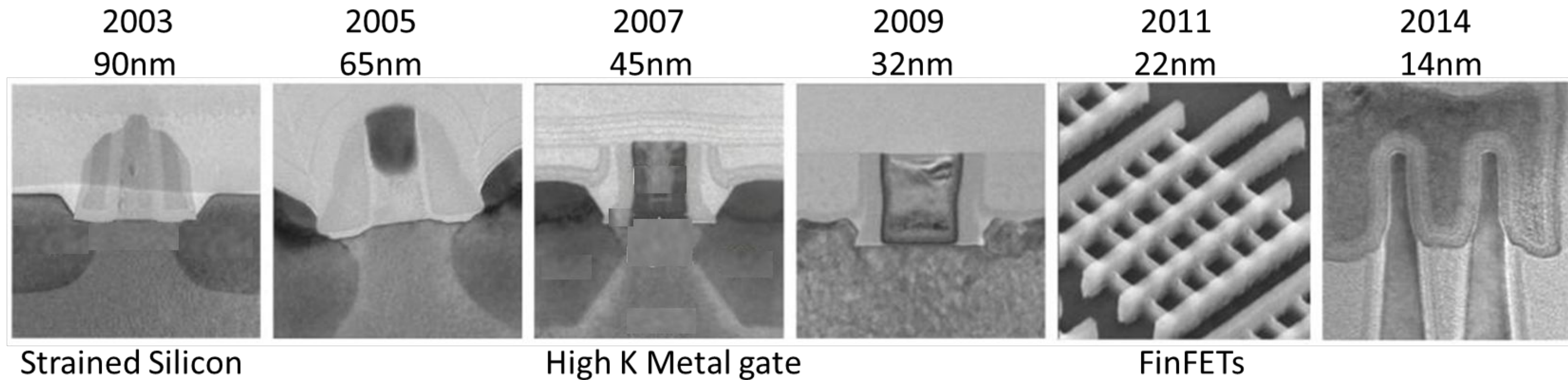
# Non Ideal Scaling



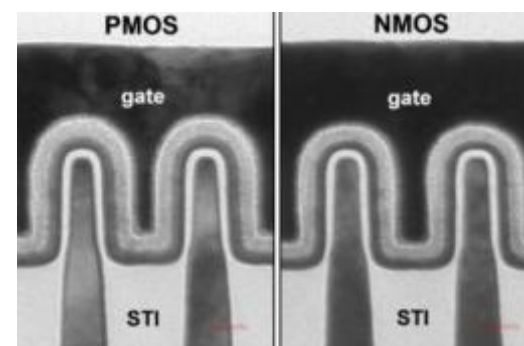
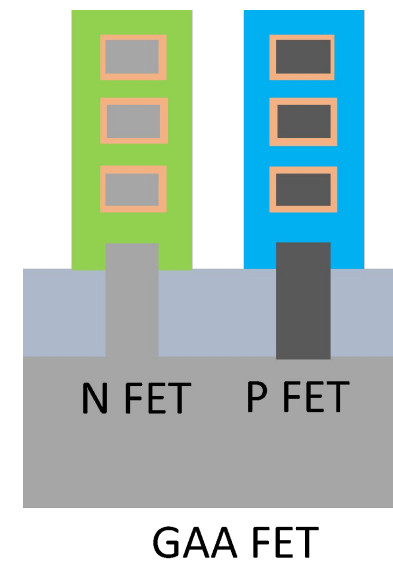
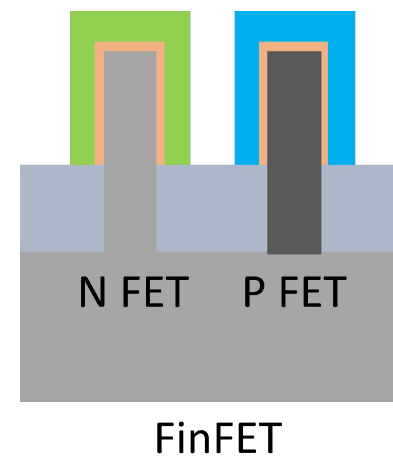
$$\text{Inverse slope} = \frac{kT}{q} \ln(10) = \frac{60\text{mV}}{\text{decade current (I)}}$$



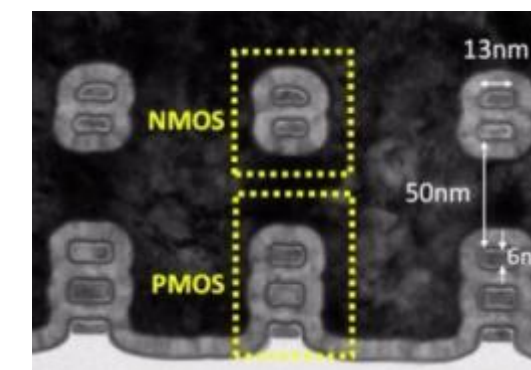
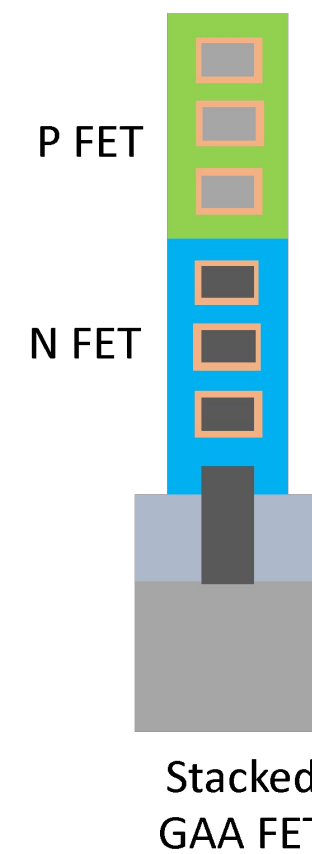
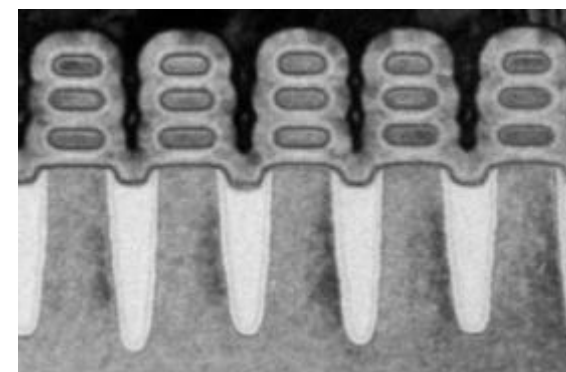
# Beyond Ideal Scaling - Innovations



# The two limited Regimes



TSMC



Intel

